Texas Instruments Inc. (DUNS# 00-732-1904) Supplier Name:

Contact Info:

ti.com/support
Distribute - RoHS and IEC 62474 DB Form/Declaration Type:

05/06/2022

Details for "TLC27M4IDR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLC27MAIDR	NIDDALI	Level-1-260C-LINLIM	ΤΙ ΤΔΙWΔΝ Δ/Τ	D I 14	3 011/2 65/1 52	1/19.8

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level		
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm	
Bond Wire								
Copper and Its Alloys	Copper	7440-50-8	0.07981	99.998747	999987	0.053275	533	
Precious Metals	Silver	7440-22-4	0.000001	0.001253	13	0.000001	0	
Sub-Total			0.079811	100	1000000	0.053275	533	
Die Attach Adhesive								
Precious Metals	Silver	7440-22-4	0.737542	80.000043	800000	0.492324	4923	
Thermoplastics	Ероху	85954-11-6	0.184385	19.999957	200000	0.123081	1231	
Sub-Total			0.921927	100	1000000	0.615405	6154	
Lead Frame								
Copper and Its Alloys	Copper	7440-50-8	42.645846	97.424999	974250	28.466979	284670	
Copper and Its Alloys	Iron	7439-89-6	1.050552	2.4	24000	0.701265	7013	
Copper and Its Alloys	Phosphorus	7723-14-0	0.006566	0.015	150	0.004383	44	
Copper and Its Alloys	Tin	7440-31-5	0.013132	0.03	300	0.008766	88	
Copper and Its Alloys	Zinc	7440-66-6	0.043773	0.1	1000	0.029219	292	
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.013132	0.03	300	0.008766	88	
Sub-Total			43.773001	100	1000000	29.219378	292194	
Lead Frame Plating								
Nickel and Its Alloys	Nickel	7440-02-0	0.120802	95.119685	951197	0.080638	806	
Precious Metals	Gold	7440-57-5	0.000991	0.780315	7803	0.000662	7	
Precious Metals	Palladium	7440-05-3	0.005207	4.1	41000	0.003476	35	
Sub-Total			0.127	100	1000000	0.084775	848	
Mold Compound								
Other Inorganic Materials	Fused Silica	60676-86-0	89.665342	88.000001	880000	59.85346	598535	
Other Plastics and Rubber	Carbon Black	1333-86-4	0.305677	0.3	3000	0.204046	2040	
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.560408	0.55	5500	0.374084	3741	
Thermoplastics	Epoxy	85954-11-6	11.361006	11.15	111500	7.583705	75837	
Sub-Total			101.892433	100	1000000	68.015295	680153	
Semiconductor Device		•		•	•			
Ceramics / Glass	Doped Silicon	7440-21-3	3.013946	100	1000000	2.011871	20119	
Sub-Total			3.013946	100	1000000	2.011871	20119	
Total			149.808118		_	100	1000000	

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm

for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.

See Glossary of Terms for more details.

Important Part Information

T. There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

For an explanation of the methods used to determine material weights, See Product Content Methodology

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

Ti bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. Ti may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. Il and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

For additional information, please contact TI customer support.

Signature: (click here for a fuller statement with a signed certificate)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality For further environmental statements, please go to www.ti.com/ecoinfo Created on: 05/06/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials.

Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

ROHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in http://www.ti.com/lit/pdf/szg088

Green: Means the content of Chlorine (CI) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <= 1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.